

ABSTRACT OF THE DISCLOSURE

5 A semiconductor package including a dam and a method for fabricating the same are provided. The semiconductor package comprises a package substrate, a semiconductor chip attached to the substrate, a TIM formed on the semiconductor chip, a dam that substantially surrounds the TIM, and a lid placed over the TIM to contact a surface thereof.

Thus, a TIM can be prevented from flowing down from the original position at high temperatures. Therefore, the performance of the semiconductor package does not deteriorate even at high temperatures.